

NLAS4717

4.5 Ω High Bandwidth, Dual SPDT Analog Switch

The NLAS4717 is an advanced CMOS analog switch fabricated in sub-micron silicon gate CMOS technology. The device is a dual independent Single Pole Double Throw (SPDT) switch featuring two low $R_{DS(on)}$ of 4.5 Ω at 3.0 V.

The device also features guaranteed Break-Before-Make (BBM) switching, assuring the switches never short the driver.

The NLAS4717 is available in two small size packages:

- ♦ Micro10: 3.0 x 5.0 mm
- ♦ Flip-Chip-10: 2.0 x 1.5 mm

Features

- Low $R_{DS(on)}$: 4.5 Ω @ 3.0 V
- Matching Between the Switches $\pm 0.5 \Omega$
- Wide Low Voltage Range: 1.8 V to 5.5 V
- High Bandwidth > 40 MHz
- 1.65 V to 5.5 V Operating Range
- Low Threshold Voltages on Pins 4 and 8 (CTRL Pins)
- Ultra-Low Charge Injection ≤ 6.0 pC
- Low Standby Current – $I_{CC} = 1.0$ nA (Max) @ $T_A = 25^\circ\text{C}$
- OVT* on Pins 4 and 8 (CTRL Logic Pins)
- Pb-Free Packages are Available

Typical Applications

- Cell Phones
- PDAs
- MP3s
- Digital Still Cameras

Important Information

- ESD Protection:
HBM = 2000 V, MM = 200 V
- Latchup Max Rating: 200 mA (Per JEDEC EIA/JESD78)
- Pin-to-Pin Compatible with MAX4717

*OVT

- Overvoltage Tolerance (OVT) specific pins to operate higher than normal supply voltages, with no damage to the devices or to signal integrity.



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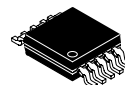
<http://onsemi.com>

MARKING DIAGRAMS

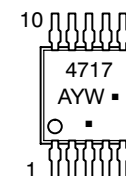
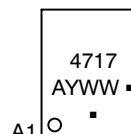


A1

**FLIP-CHIP-10
CASE 489AA**



**Micro10
CASE 846B**



A = Assembly Location
Y = Year
W, WW = Work Week
▪ = Pb-Free Package

FUNCTION TABLE

IN ₋	NO ₋	NC ₋
0	OFF	ON
1	ON	OFF

ORDERING INFORMATION

Device	Package	Shipping [†]
NLAS4717FCT1	Flip-Chip-10	3000 / Tape & Reel
NLAS4717FCT1G	Flip-Chip-10 (Pb-Free)	3000 / Tape & Reel
NLAS4717MR2	Micro10	4000 / Tape & Reel
NLAS4717MR2G	Micro10 (Pb-Free)	4000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

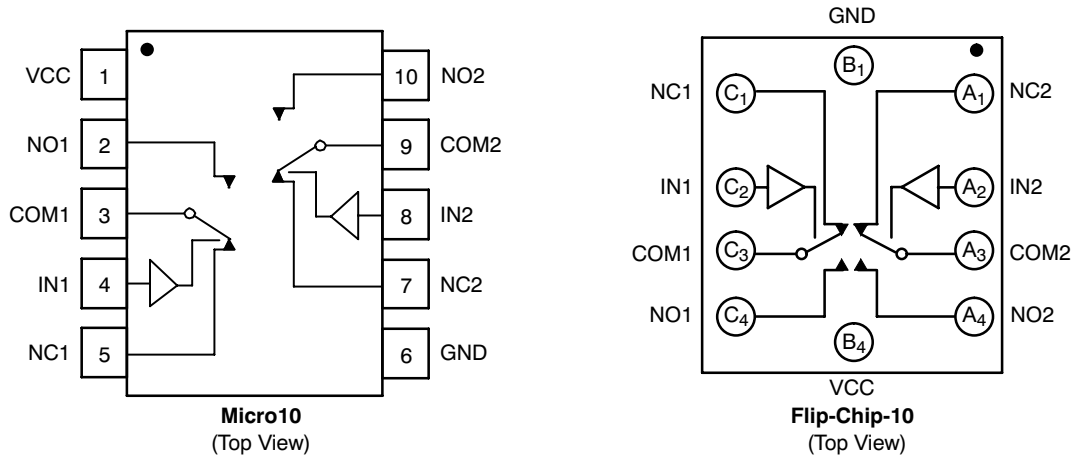


Figure 1. Device Circuit Diagrams and Pin Configurations

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V+	Positive DC Supply Voltage	-0.5 to +7.0	V
V _{IS}	Analog Input Voltage (V _{NO} , V _{NC} , or V _{COM}) (Note 1)	-0.5 ≤ V _{IS} ≤ V _{CC} + 0.5	V
V _{IN}	Digital Select Input Voltage	-0.5 ≤ V _I ≤ +7.0	V
I _{IK}	DC Current, Into or Out of Any Pin (Continuous)	±100	mA
I _{PK}	Peak Current (10% Duty Cycle)	±200	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Signal voltage on NC, NO, and COM exceeding V_{CC} or GND are clamped by the internal diodes. Limit forward diode current to maximum current rating.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V+	DC Supply Voltage	1.8	5.5	V
V _{IN}	Digital Select Input Voltage	GND	5.5	V
V _{IS}	Analog Input Voltage (NC, NO, COM)	GND	V _{CC}	V
T _A	Operating Temperature Range	-40	+85	°C
t _r , t _f	Input Rise or Fall Time, SELECT	V _{CC} = 3.3 V ± 0.3 V V _{CC} = 5.0 V ± 0.5 V		ns/V
		0	100	
		0	20	

ANALOG SWITCH DC CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	-40 °C to +85 °C		Unit
				Min	Max	
V _{IH}	Input Logic High Voltage	V _{OUT} = 0.1 V I _{OUT} ≤ 20 μA	1.65 to 2.2 2.7 to 3.6 4.5 to 5.5	V _{CC} × 0.55 V _{CC} × 0.5 2.0	- - -	V
V _{IL}	Input Logic Low Voltage	V _{OUT} = -V _{CC} - 0.1 V I _{OUT} ≤ 20 μA	1.65 to 2.2 2.7 to 3.6 4.5 to 5.5	- - -	V _{CC} × 0.2 V _{CC} × 0.2 0.8	V
I _{IN}	Input Leakage Current	V _{IN} - V _{CC} or GND	5.0	-100	+100	nA
V _{CC}	Power Supply Range	All	-	1.65	5.5	V
I _{CC}	Supply Current	V _{IN} = V _{CC} or GND I _{OUT} = 0 μA	1.8 3.3 5.0	- - -	1.0 1.0 1.0	μA
V _{IS}	Analog Signal Range	Key parameter	-	0	V _{CC}	V

ANALOG SWITCH CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

Symbol	Parameter	Condition	V _{CC} (V)	-40 °C to +85°C			Unit
				Min	Typ	Max	
R _{ON}	ON Resistance (Note 2)	V _{CC} = 3.0 V I _{COM} = 10 mA V _{NO} or V _{NC} = V _{IH} or V _{IL}	3.0	-		4.5	Ω
		V _{CC} = 5.0 V I _{COM} = 10 mA V _{NO} or V _{NC} = V _{IH} or V _{IL}	5.0	-		3.5	
ΔR _{ON}	ON Resistance Match Between Channels (Note 2 and 3)	V _{CC} = 3.6 V I _{COM} = 10 mA V _{NO} or V _{NC} = V _{IH} or V _{IL}	3.6	-	0.1	0.4	Ω
		V _{CC} = 5.5 V I _{COM} = 10 mA V _{NO} or V _{NC} = V _{IH} or V _{IL}	5.5				
R _{FLAT[ON]}	ON Resistance Flatness (Note 4)	I _{COM} = 10 mA V _{IS} = 0 to V _{CC}	3.0	-		1.5	Ω
		I _{COM} = 10 mA V _{IS} = 0 to V _{CC}	5.5	-		1.36	
I _{NO_[OFF]} I _{NC_[OFF]}	NO_, NC_ Off-Leakage Current (Note 5)	V _{CC} = 3.6 V V _{COM} = 0.3 V or 3.3 V V _{NO} or V _{NC} = 0.3 V or 3.3 V	3.6	-1.0	0.01	+1.0	nA
		V _{CC} = 5.5 V V _{COM} = 0 V or 5.0 V V _{NO} or V _{NC} = 0 V or 5.0 V	5.5	-1.0	0.01	+1.0	
I _{COM_[ON]}	COM_ On-Leakage Current (Note 5)	V _{CC} = 3.6 V V _{COM} = 0.3 V or 3.3 V V _{NO} or V _{NC} = 0.3 V or 3.3 V	3.6	-2.0	0.01	+2.0	nA
		V _{CC} = 5.5 V V _{COM} = 0 V or 5.0 V V _{NO} or V _{NC} = 0 V or 5.0 V	5.5	-2.0	0.01	+2.0	

ANALOG SWITCH AC CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	-40 °C to +85°C			Unit
				Min	Typ	Max	
t _{ON}	Turn-On Time	V _{NC_} , V _{NO_} = V _{IH} or V _{IL} R _L = 300 Ω, C _L = 35 pF V _{IN[x]} = V _{IH} or V _{IL}	1.8 to 5.5	-	-	30	nS
t _{OFF}	Turn-Off Time	V _{NC_} , V _{NO_} = V _{IH} or V _{IL} R _L = 300 Ω, C _L = 35 pF V _{IN[x]} = V _{IH} or V _{IL}	1.8 to 5.5	-	-	40	nS
t _{BBM}	Break-Before-Make Time Delay (Note 5)	V _{NC_} , V _{NO_} = 1.5 V R _L = 300 Ω, C _L = 35 pF	-	-	8.0	-	nS
t _{SKEW}	Skew (Note 5)	R _S = 39 Ω, C _L = 50 pF	-	-	0.15	2.0	nS

2. R_{ON} characterized for V_{CC} range (1.65 V to 5.5 V).
3. ΔR_{ON} = R_{ON}(MAX) - R_{ON}(MIN).
4. R_{FLAT[ON]} = R_{ON}(MAX) - R_{ON}(MIN), measured over V_{CC} range.
5. Guaranteed by design.

ANALOG SWITCH APPLICATION CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	-40 °C to +85°C			Unit
				Min	Typ	Max	
Q	Charge Injection	V _{IN} = V _{CC} to GND R _{IN} = 0 Ω, C _L = 1.0 nF Q = C _L · ΔV _{OUT}	3.0 5.0		6.0 9.0		pC
VISO	Off-Isolation	f = 10 MHz V _{NO_} , V _{NC_} = 1.0 Vp-p R _L = 50 Ω, C _L = 5.0 pF	1.65 to 5.5		-50		dB
		f = 1.0 MHz V _{NO_} , V _{NC_} = 1.0 Vp-p R _L = 50 Ω, C _L = 5.0 pF			-75		
VCT	Cross-Talk	f = 10 MHz V _{NO_} , V _{NC_} = 1.0 Vp-p R _L = 50 Ω, C _L = 5.0 pF	1.65 to 5.5		-80		dB
		f = 1.0 MHz V _{NO_} , V _{NC_} = 1.0 Vp-p R _L = 50 Ω, C _L = 5.0 pF			-110		
BW	On-Channel -3.0 db Bandwidth	Signal = 0 dB R _L = 50 Ω, C _L = 5.0 pF	1.8 to 5.0		40		MHz
THD	Total Harmonic Distortion	V _{COM} = 2.0 Vp-p, R _L = 600 Ω, T _A = 25°C	-		0.02		%
C _{NO_[OFF]} C _{NC_[OFF]}	NO_, NC_ OFF-Capacitance	F = 10 MHz	-		30		pF
C _{NO_[ON]} C _{NC_[ON]}	NO_, NC_ ON-Capacitance	F = 10 MHz	-		110		pF

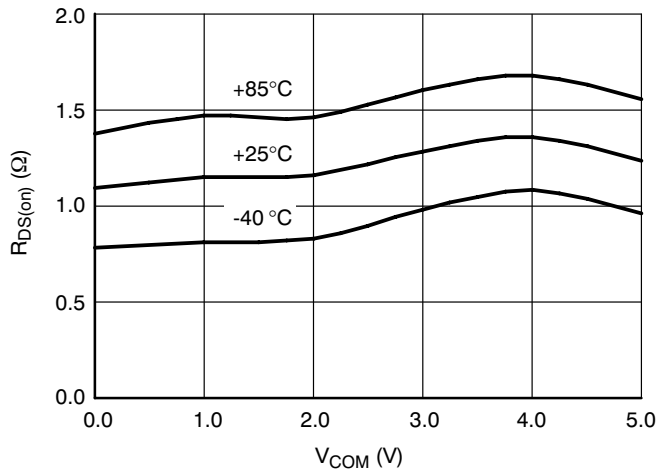


Figure 2. Low $R_{DS(on)}$ @ $V_{CC} = 5.0$ V

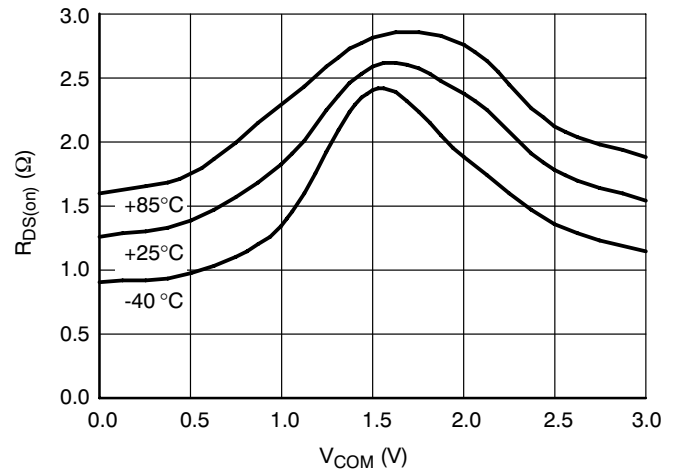


Figure 3. Low $R_{DS(on)}$ @ $V_{CC} = 3.0$ V

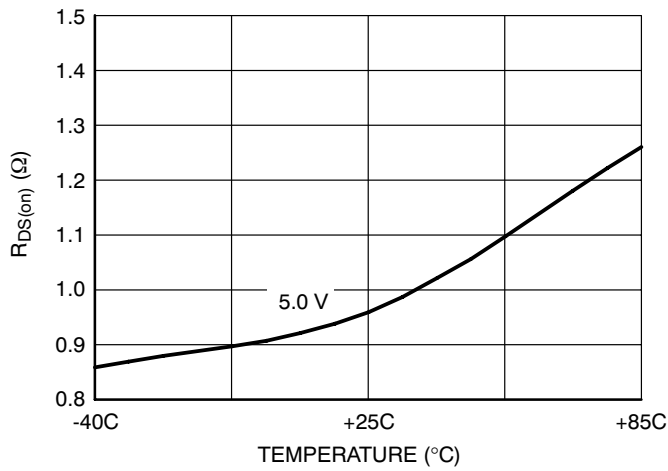


Figure 4. $\Delta R_{DS(on)}$ @ $V_{CC} = 5.0$ V

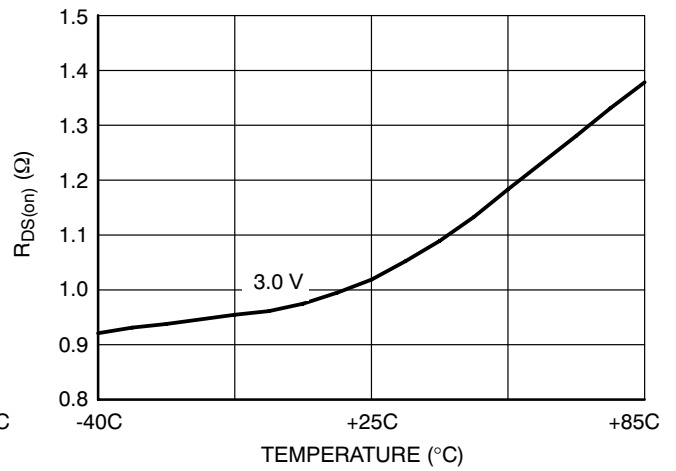


Figure 5. $\Delta R_{DS(on)}$ @ $V_{CC} = 3.0$ V

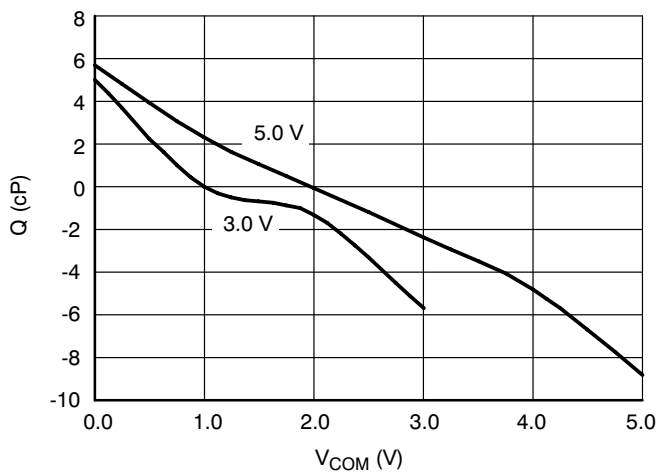


Figure 6. Charge Injection

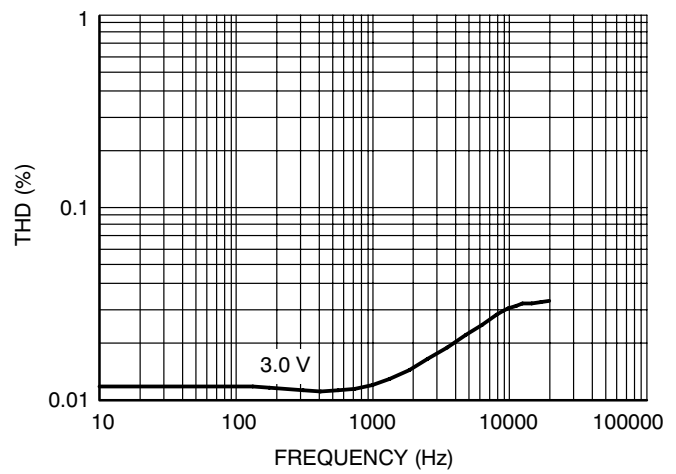


Figure 7. Total Harmonic Distortion

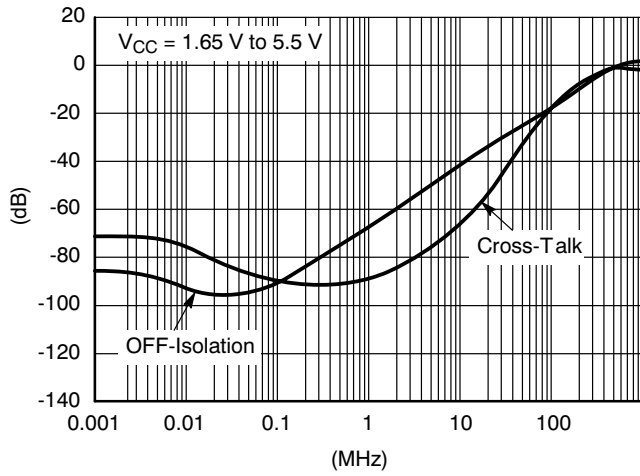


Figure 8. Frequency Response

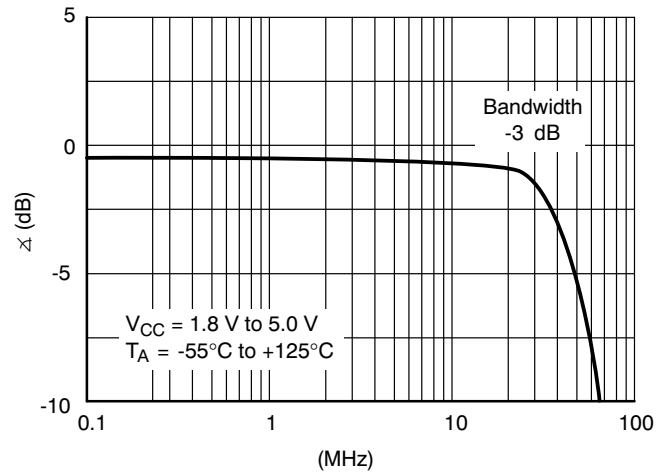


Figure 9. Bandwidth and Phase

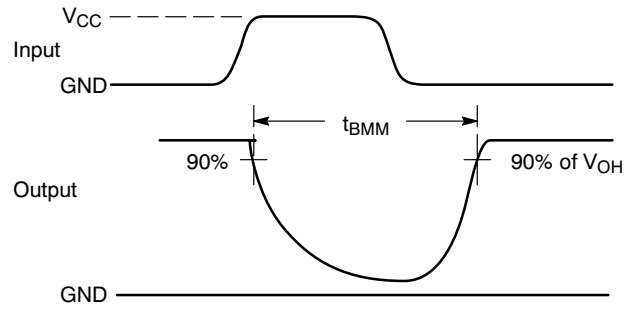
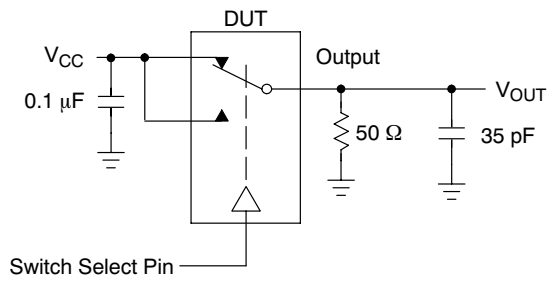


Figure 10. t_{BMM} (Time Break-Before-Make)

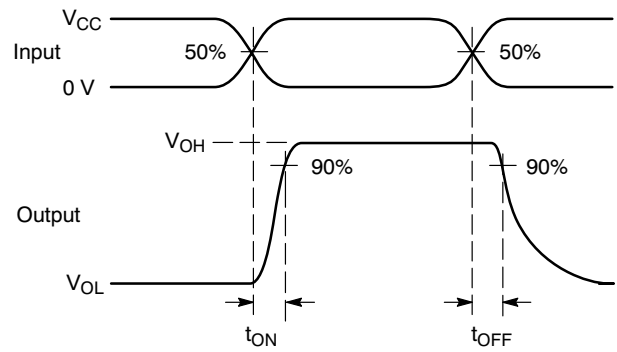
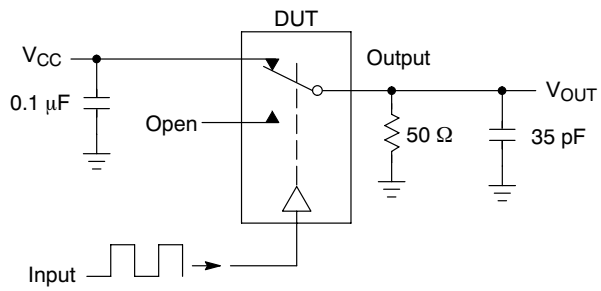


Figure 11. t_{ON}/t_{OFF}

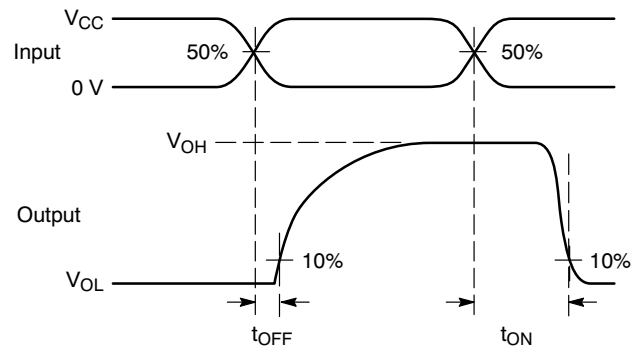
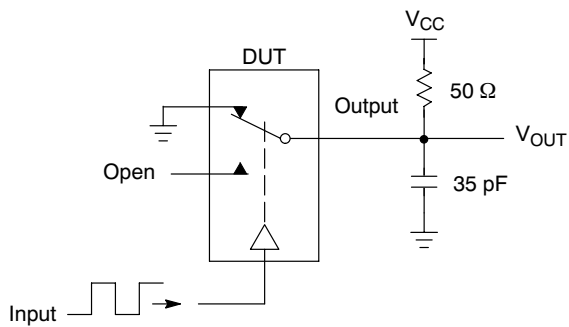
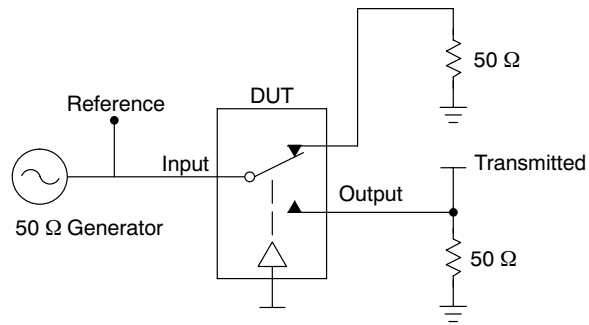


Figure 12. t_{ON}/t_{OFF}



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. V_{ISO} , Bandwidth and V_{ONL} are independent of the input signal direction.

$$V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log} \left(\frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz}$$

$$V_{ONL} = \text{On Channel Loss} = 20 \text{ Log} \left(\frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz}$$

Bandwidth (BW) = the frequency 3.0 dB below V_{ONL}

V_{CT} = Use V_{ISO} setup and test to all other switch analog input/outputs terminated with 50 Ω

Figure 13. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/ V_{ONL}

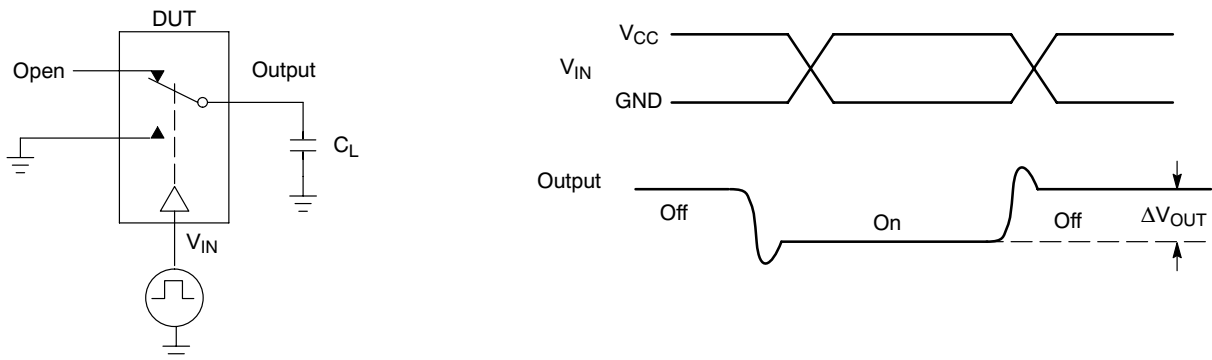
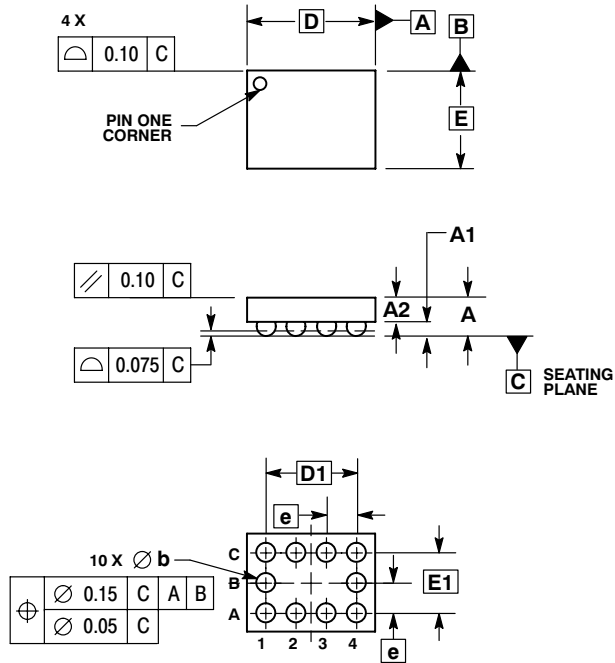


Figure 14. Charge Injection: (Q)

NLAS4717

PACKAGE DIMENSIONS

10 PIN FLIP-CHIP CASE 489AA-01 ISSUE A



NOTES:

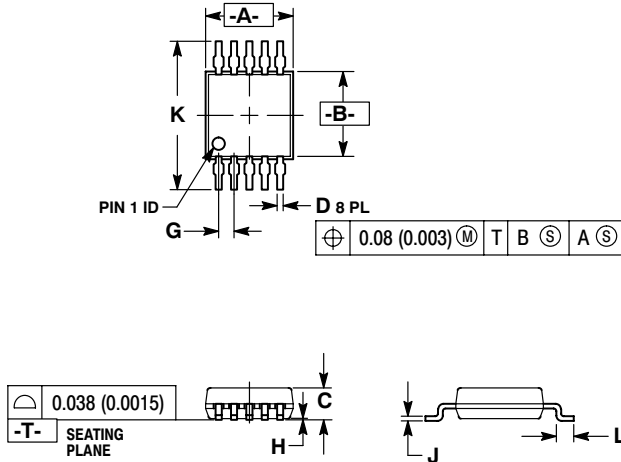
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.650
A1	0.210	0.270
A2	0.280	0.380
D	1.965 BSC	
E	1.465 BSC	
b	0.250	0.350
e	0.500 BSC	
D1	1.500 BSC	
E1	1.000 BSC	

NLAS4717

PACKAGE DIMENSIONS

Micro10
CASE 846B-03
ISSUE D

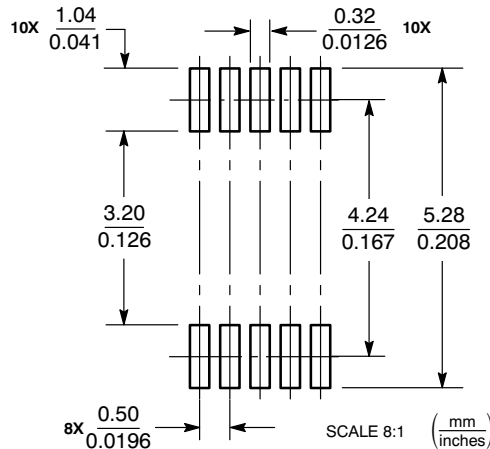


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION "B" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846B-01 OBSOLETE. NEW STANDARD 846B-02

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.95	1.10	0.037	0.043
D	0.20	0.30	0.008	0.012
G	0.50 BSC		0.020 BSC	
H	0.05	0.15	0.002	0.006
J	0.10	0.21	0.004	0.008
K	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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